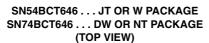
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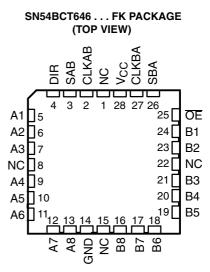
- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Bus Transceivers/Registers
- Independent Registers and Enables for A and B Buses



CLKAB	۵	1	U	24	b	V _{CC}
SAB	[2		23	þ	CLKBA
DIR	Π	3		22	þ	SBA
A1	С	4		21	þ	OE
A2	[5		20	þ	B1
A3	Π	6		19	0	B2
A4	[7		18	þ	B3
A5		8		17		B4
A6		9		16	p	B5
A7		10		15	p	B6
A8		11		14		B7
GND	Q	12		13	p	B8

- Multiplexed Real-Time and Stored Data
- ESD Protection Exceeds JESD 22

 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)



NC - No internal connection

description/ordering information

These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'BCT646 devices.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus will receive data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data can be stored in one register and/or B data can be stored in the other register.

T _A	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74BCT646NT	SN74BCT646NT
0°C to 70°C		Tube	SN74BCT646DW	DOTO
	SOIC – DW	Tape and reel	SN74BCT646DWR	BCT646
	CDIP – JT	Tube	SNJ54BCT646JT	SNJ54BCT646JT
–55°C to 125°C	CFP – W	Tube	SNJ54BCT646W	SNJ54BCT646W
	LCCC – FK	Tube	SNJ54BCT646FK	SNJ54BCT646FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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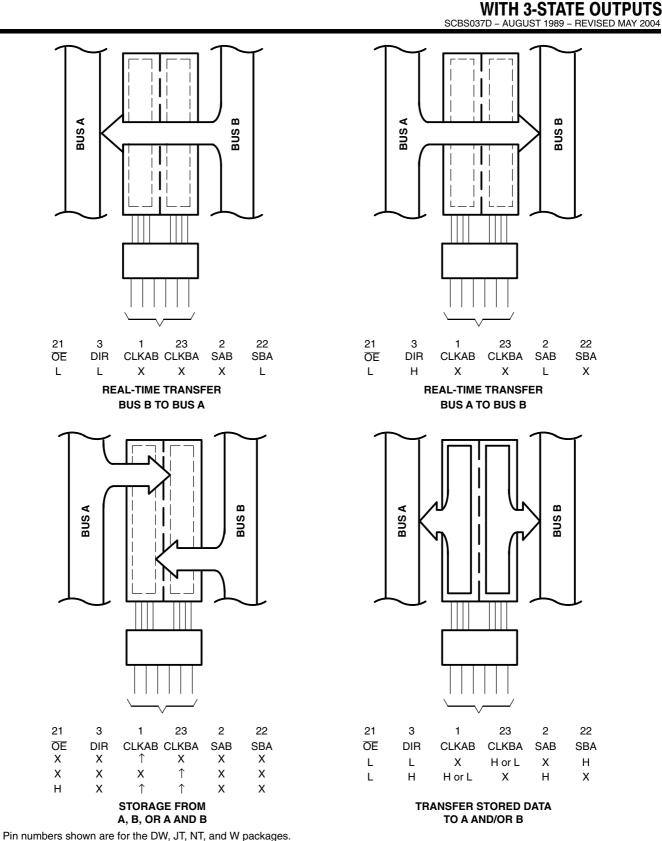
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description/ordering information(continued)

When an output function is disabled, the input function still is enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.





n numbers shown are for the DW, JT, NT, and W packages.





SN54BCT646, SN74BCT646

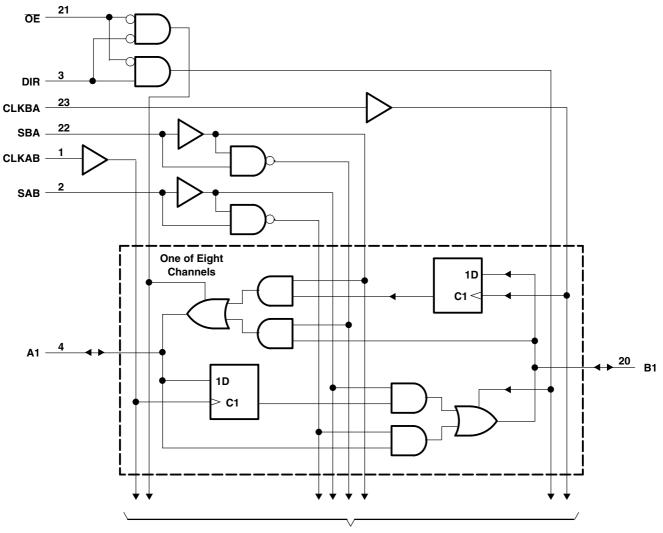
OCTAL BUS TRANSCEIVERS AND REGISTERS

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	FUNCTION TABLE												
INPUTS						DAT	A I/O						
ŌE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION					
Х	Х	Ŷ	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]					
х	х	Х	\uparrow	х	Х	Unspecified [†]	Input	Store B, A unspecified [†]					
Н	Х	Ŷ	\uparrow	Х	Х	Input	Input	Store A and B data					
н	х	H or L	H or L	х	Х	Input disabled	Input disabled	Isolation, hold storage					
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus					
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus					
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus					
L	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus					

[†] The data output functions can be enabled or disabled by various signals at the OE and DIR inputs. Data input functions always are enabled, i.e., data at the bus pins is stored on every low-to-high transition of the clock inputs.

logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DW, JT, NT, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range: Control inputs (see Note 1)	
I/O ports (see Note 1)	–0.5 V to 5.5 V
Voltage range applied to any output in the disabled or power-off state, Vo	–0.5 V to 7 V
Voltage range applied to any output in the high state, Vo	\ldots –0.5 V to V _{CC}
Current into any output in the low state: SN54BCT646	96 mA
SN74BCT646	128 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

3. The package thermal impedance is calculated in accordance with JESD 51-3.

recommended operating conditions (see Note 4)

		SN	54BCT6	46	SN			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{IK}	Input clamp current			-18			-18	mA
I _{OH}	High-level output current			-12			-15	mA
I _{OL}	Low-level output current			48			64	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER				SN	54BCT6	46	SN			
Р	ARAMETER	TES	ST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = –18 mA			-1.2			-1.2	V
			I _{OH} = -3 mA	2.4	3.3		2.4	3.3		
V _{OH}		V _{CC} = 4.5 V	I _{OH} = -12 mA	2	3.2					v
			I _{OH} = -15 mA				2	3.1		
.,			I _{OL} = 48 mA		0.38	0.55				.,
V _{OL}		$V_{CC} = 4.5 V$	I _{OL} = 64 mA					0.42	0.55	V
	A or B port					1			1	
II	Control inputs $V_{CC} = 5.5 V$,	V _I = 5.5 V			1			1	mA	
. +	A or B port					70			70	
IIH‡	Control inputs	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
. +	A or B port		N 05V			-0.7			-0.7	
I _{IL} ‡	Control inputs	V _{CC} = 5.5 V,	V _I = 0.5 V		-0.7				-0.7	mA
los§		V _{CC} = 5.5 V,	V _O = 0	-100		-225	-100		-225	mA
I _{CCL}	A or B port	V _{CC} = 5.5 V,	$V_I = GND$		42	67		42	67	mA
I _{CCH}	A or B port	V _{CC} = 5.5 V,	V _I = 4.5 V		5.6	9		5.6	9	mA
I _{CCZ}	A or B port	V _{CC} = 5.5 V,	V _I = GND		10	16		10	16	mA
Ci	Control inputs	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		6			6		pF
Cio	A or B port	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		12			14		pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V _{CC} T _A =	= 5 V, 25°C	SN54B	SN54BCT646		CT646	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		83		83		83	MHz
tw	Pulse duration, CLK high or low	6		6		6		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	6		7		6		ns
t _h	Hold time, A or B after CLKAB \uparrow or CLKBA \uparrow	0.5		0.5		0.5		ns



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

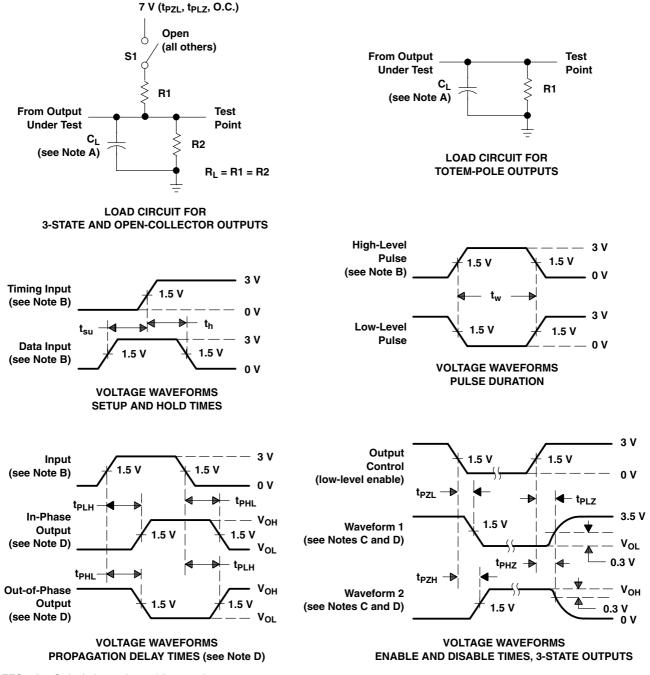
PARAMETER	FROM	то		V _{CC} = 5 V, T _A = 25°C			CT646	SN74BCT646		UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}			83			83		83		MHz	
t _{PLH}		A	3.6	7	9.4	3.6	12.4	3.6	11.2		
t _{PHL}	CLKBA or CLKAB	A or B	3.9	7	9.2	3.9	11.5	3.9	10.6	ns	
t _{PLH}	A or B	B or A	3.1	6	8.1	3.1	11.1	3.1	9.5		
t _{PHL}	AOLP	D OF A	3.7	6.8	8.9	3.7	12.1	3.7	10.5	ns	
t _{PLH}	SAB or SBA [†]	A cu D	4.5	8.8	11.2	4.5	15.2	4.5	13.8		
t _{PHL}	(with A or B high)	A or B	3.3	6	8.1	3.3	9.8	3.3	9.1	ns	
t _{PLH}	SAB or SBA [†]	A	3.9	7.7	10.2	3.9	13.3	3.9	12		
t _{PHL}	(with A or B low)	A or B	4.7	8.3	10.8	4.7	13.7	4.7	12.9	ns	
t _{PZH}	OE	A or D	4	7.9	10.7	4	14	4	13.2	5	
t _{PZL}	UE	A or B	4.6	8.8	11.8	4.6	15.4	4.6	14.4	ns	
t _{PHZ}	OE	A cri D	4	7.2	9.4	4	12	4	10.9		
t _{PLZ}	UE	A or B	3.4	7	9.3	3.4	11.6	3.4	10.5	ns	
t _{PZH}	DID	A cri D	2.8	7.8	10.7	2.8	14	2.8	13.1		
t _{PZL}	DIR	A or B	3.8	8.9	11.9	3.8	15.6	3.8	14.6	ns	
t _{PHZ}	DIR	A or B	3.8	8.4	10.7	3.8	13.2	3.8	12.6	-	
t _{PLZ}		AUD	3.2	7.3	9.9	3.2	12.6	3.2	11.8	ns	

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



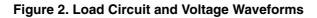
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NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, t_r = t_f ≤ 2.5 ns, duty cycle = 50%.
 C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- F. All parameters and waveforms are not applicable to all devices.







PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9155501M3A	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9155501M3A SNJ54BCT 646FK	Samples
5962-9155501MLA	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9155501ML A SNJ54BCT646JT	Samples
SN74BCT646DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT646	Samples
SN74BCT646DWE4	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT646	Samples
SNJ54BCT646FK	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9155501M3A SNJ54BCT 646FK	Samples
SNJ54BCT646JT	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9155501ML A SNJ54BCT646JT	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

9-Mar-2021

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54BCT646, SN74BCT646 :

- Catalog: SN74BCT646
- Military: SN54BCT646

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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